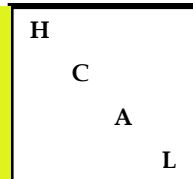




Upgrade Workshop



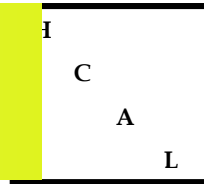
CMS HCAL Working Group FE Electronics: New GOL Nov 20, 2007

**HCAL personnel interested in GOL/GBT: Jeremy Mans, Tullio Grassi,
Drew Baden, Chris Tully, Julie Whitmore**

**Slides borrowed from Chris Tully, Paolo Moreira, Sandro Marchioro, Jan Troska,
Jorgen Christiansen, Terri Shaw**



6 Channel FE Board



Custom ASICs

QIE (6 / board)
Fermilab

Low Voltage Regulator
(2 / board) CERN
Developed in rad hard process

AD590
Temp Sensor

P82B96
I2C Transceiver
(change to P82B715)

Honeywell
VCSEL
HFE419x-521
(2/board)
[back side of
board]

MC100LVELT23
LVPECL-LVTTL

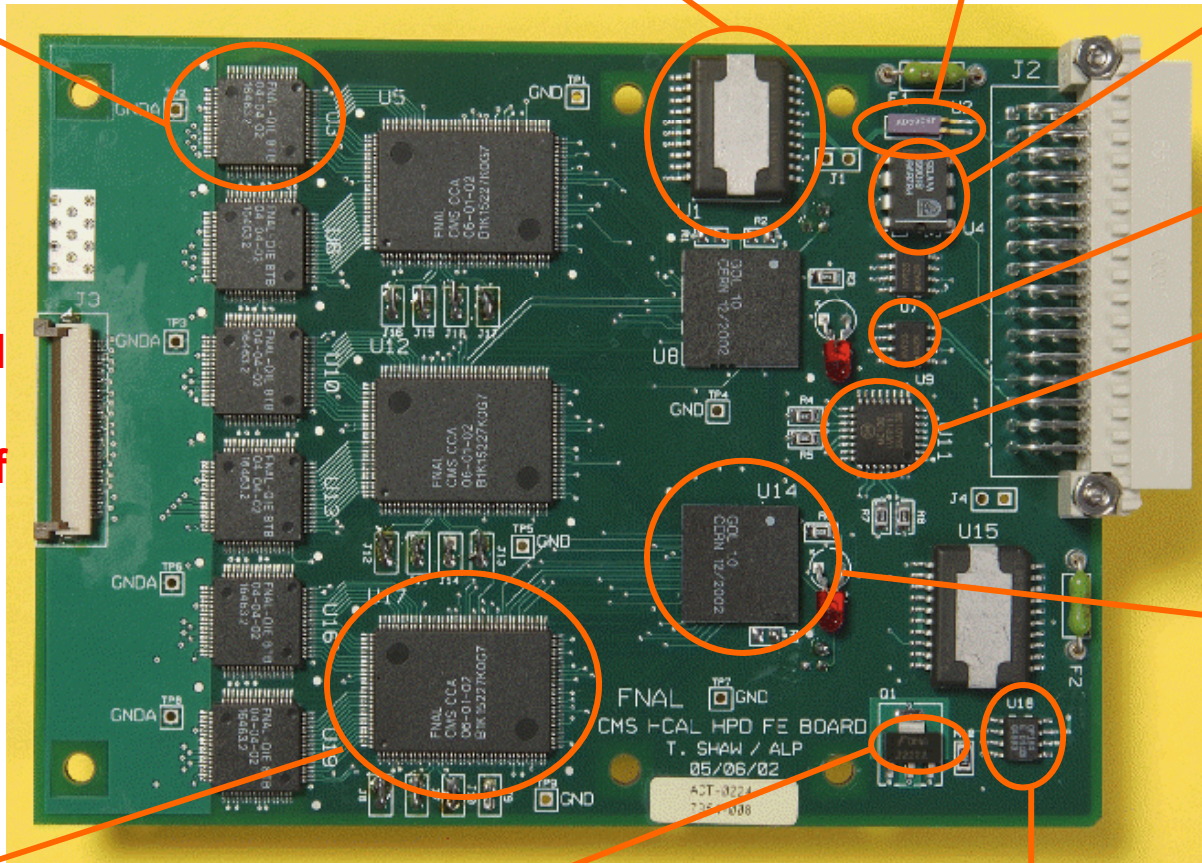
MC100LVEP111
LVPECL clock
fanout chip

Gigabit Optical
Link [GOL]
(2 / board) CERN
Developed in
rad hard process

CCA
(3 / board)
Fermilab

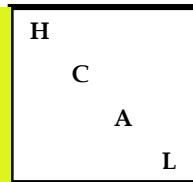
PZT222A transistor

OP184 bi-polar OpAmp

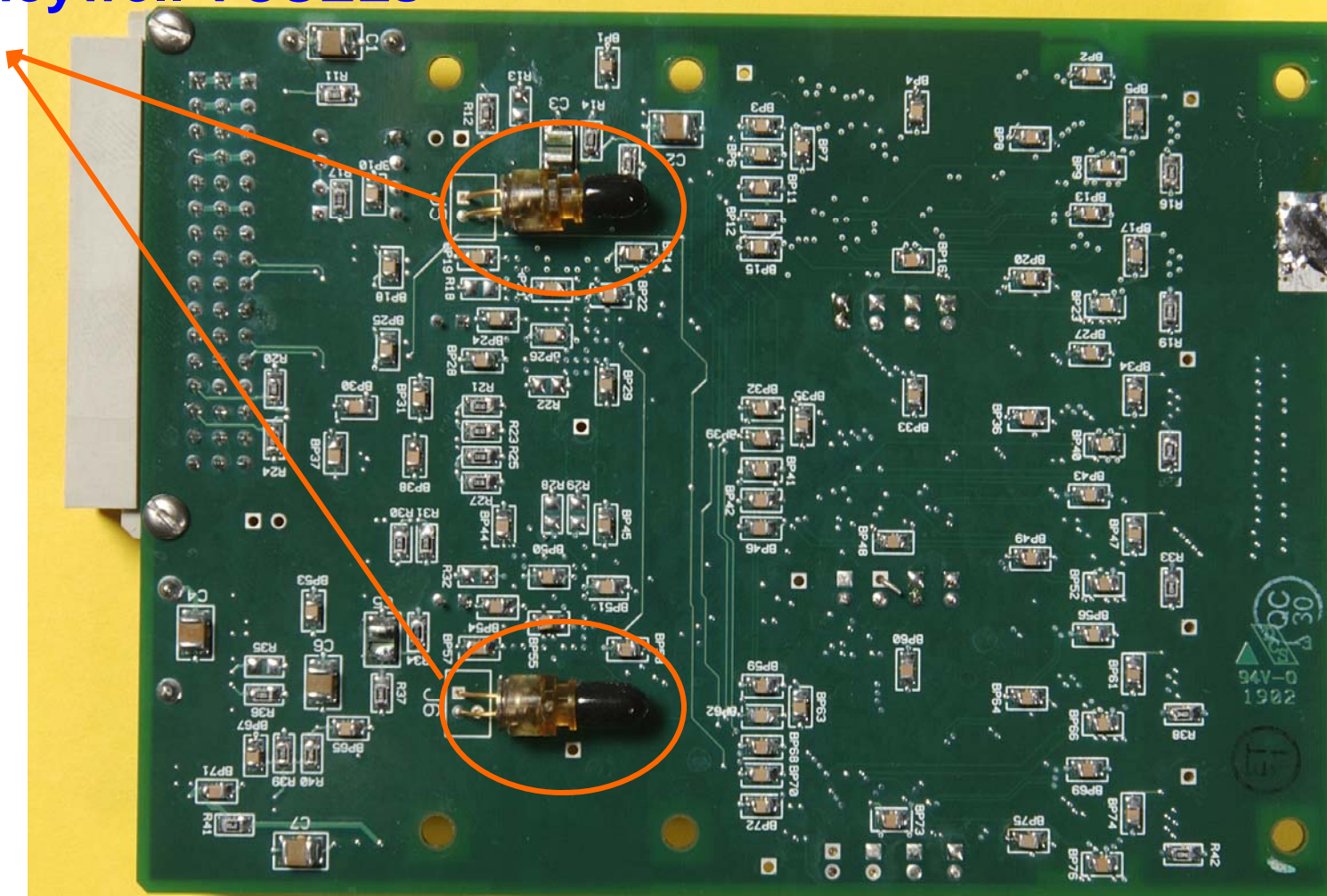




6 Channel FE Board (Backside)

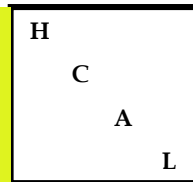


Honeywell VCSELs

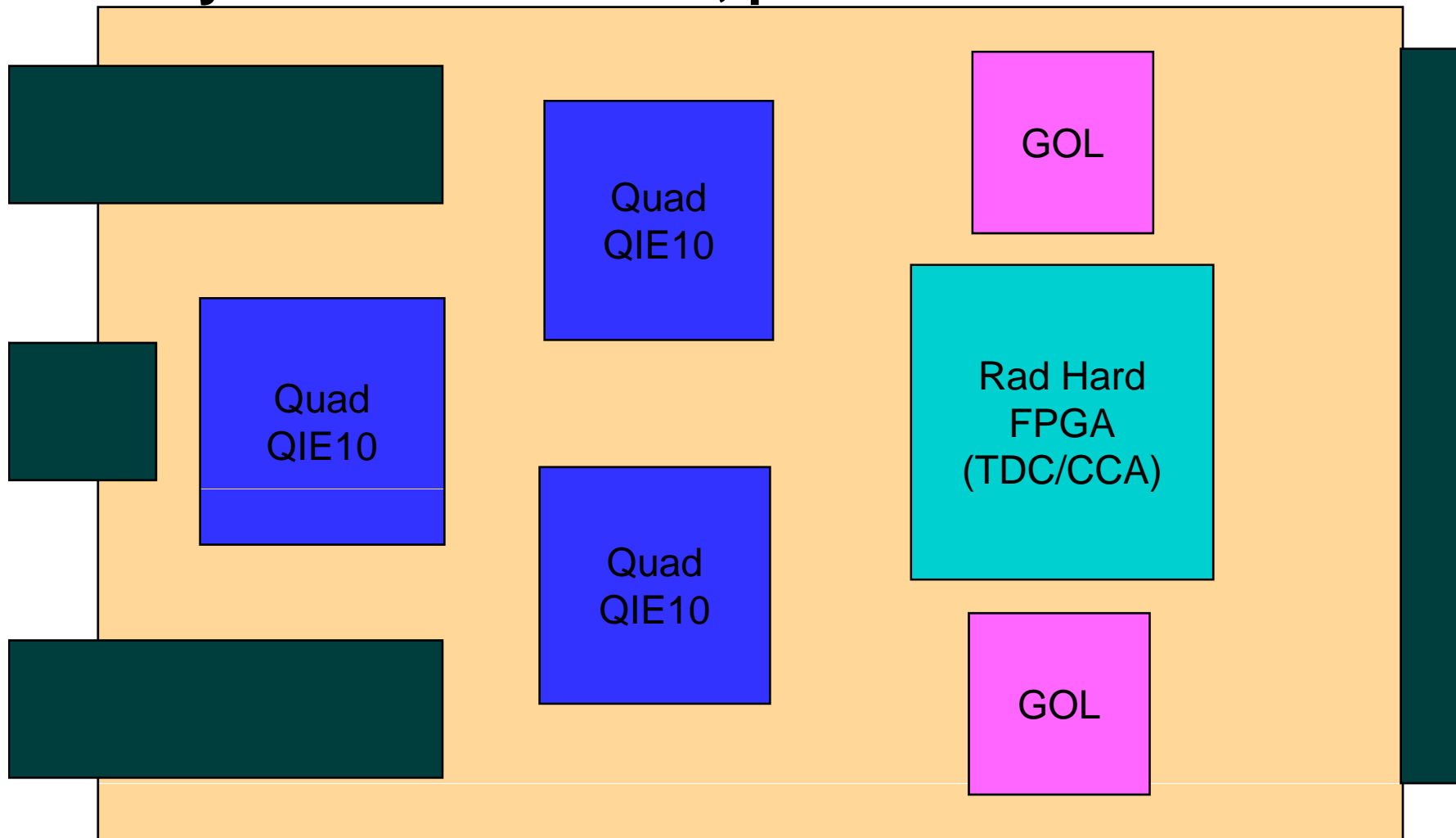




QIE10 12-Channel Cards

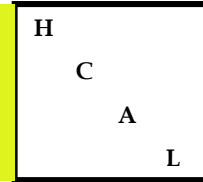


3 layers/tower - 1 inner, plus 2 inter-weaved outer





HB Digital Readout Bandwidth



Current Readout (1.6 GHz) Format

	D(31:30)	D(29:25)	D(24)	D(23:22)	D(21:17)	D(16)	D(15:14)	D(13:9)	D(8:7)	D(6:5)	D(4:3)	D(2)	D(1)	D(0)
Optical Cable 1	QIE 0 Exp (1:0)	QIE 0 Mant (4:0)	QIE_Reset (abort gap marker?)	QIE 1 Exp (1:0)	QIE 1 Mant (4:0)	"0"	QIE 2 Exp (1:0)	QIE 2 Mant (4:0)	QIE 0 CapID(1:0)	QIE 1 CapID(1:0)	QIE 2 CapID(1:0)	Control Flag=0	Data Flag=1	"1"
Optical Cable 2	QIE 4 Exp (1:0)	QIE 4 Mant (4:0)	QIE_Reset (abort gap marker?)	QIE 5 Exp (1:0)	QIE 5 Mant (4:0)	"0"	QIE 3 Exp (1:0)	QIE 3 Mant (4:0)	QIE 4 CapID(1:0)	QIE 5 CapID(1:0)	QIE 3 CapID(1:0)	Control Flag=0	Data Flag=1	"1"

FE DATA FORMAT

64 bits/25ns per fiber

Possible HB Readout (3.2 GHz) Format with GOL

QIE0 8-bit	QIE1 8-bit	QIE2 8-bit	QIE3 8-bit	QIE4 8-bit	QIE5 8-bit
---------------	---------------	---------------	---------------	---------------	---------------

TDC0 5-bit	CapID(0-3) 2-bit	ErrBit 1-bit	TDC3 5-bit	CapID(4-5) 2-bit	ErrBit 1-bit
---------------	---------------------	-----------------	---------------	---------------------	-----------------

Optical Cable 1

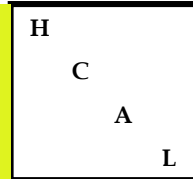
QIE6 8-bit	QIE7 8-bit	QIE8 8-bit	QIE9 8-bit	QIE10 8-bit	QIE11 8-bit
---------------	---------------	---------------	---------------	----------------	----------------

TDC6 5-bit	CapID(6-7) 2-bit	ErrBit 1-bit	TDC9 5-bit	CapID(8-11) 2-bit	ErrBit 1-bit
---------------	---------------------	-----------------	---------------	----------------------	-----------------

Optical Cable 2



GOL



Gigabit Optical Link (GOL) Configuration

- 32 bit mode; 1.6 Gb/s (8-bit/10-bit); Gigabit Ethernet Protocol
- Need to confirm max speed (3.2 Gbps?) w/ bit error rate test - UMinn
- At CERN, 30 Wafers with 1770 chips/wafer
- Packaging - (for order ~10,000, \$2.5/chip, NRE already paid)
- Place order soon to avoid re-negotiating export license

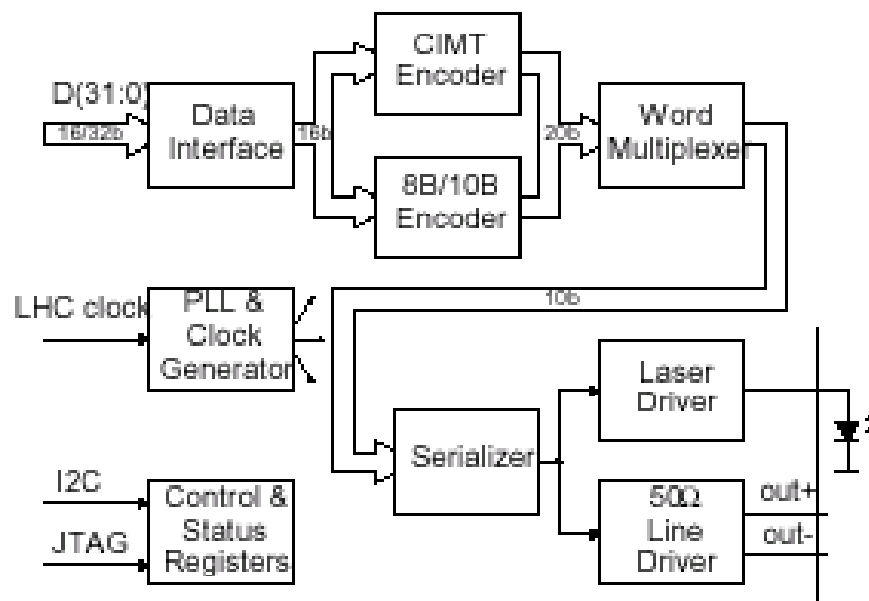
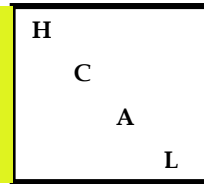




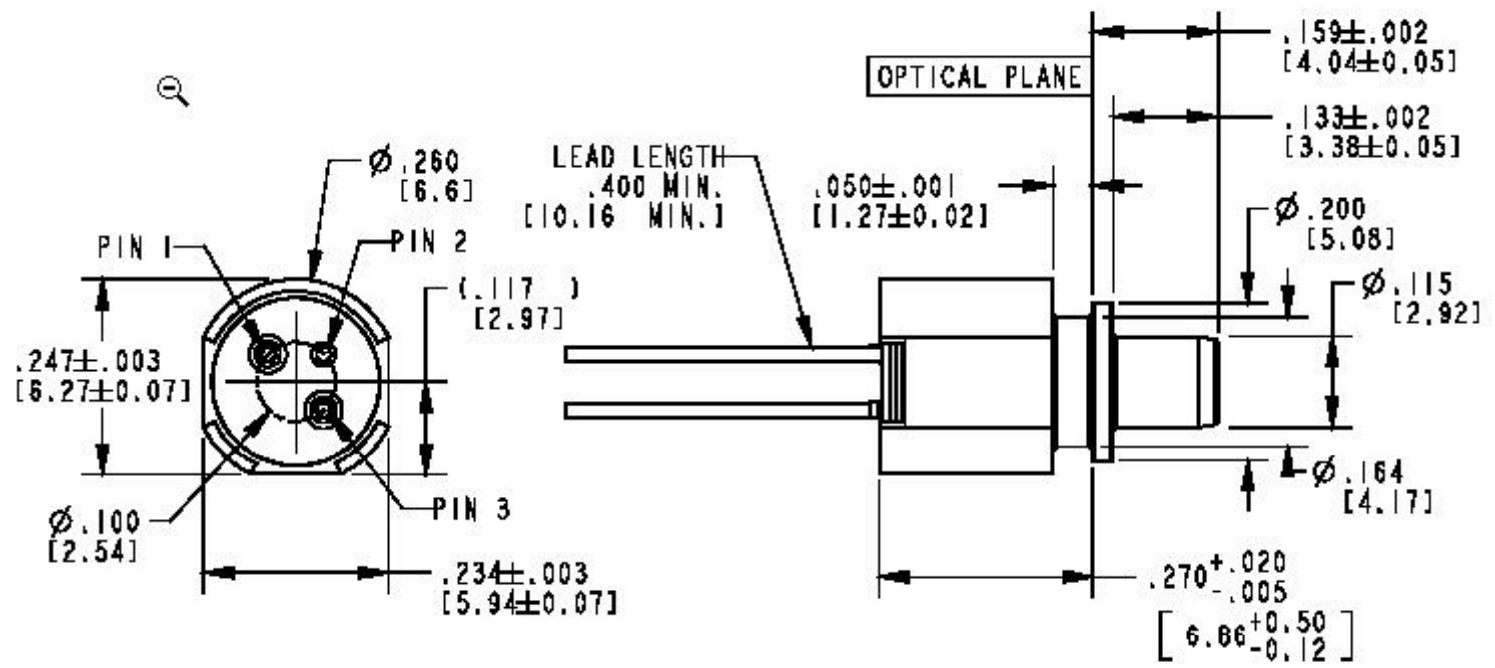
Figure 1 GOL block diagram.



Connectorized VCSEL (HPD Boards)

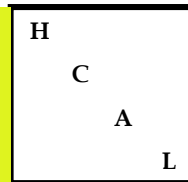


2.5Gbps VCSEL Connectorized - Datacom		
 NEW!	HFE419x-521  Product Sheet	LC Connectorized Components, Common Anode and Common Cathode, 2.5 Gb/s operation, attenuated





HCAL Fiber Bandwidth



Specifications Graded-Index Multimode Optical Fibre. Type: 50 / 125 μm



Characteristics	Conditions	Specified Values			Units
Optical Characteristics					
Attenuation Coefficient	850 nm 1300 nm	≤ 2.3 ≤ 0.5	≤ 2.4 ≤ 0.6	≤ 2.5 ≤ 0.7	[dB/km] [dB/km]
Minimum Modal Bandwidth [1,2]	850 nm 1300 nm			400 to > 1000 600 to > 1500	[MHz.km] [MHz.km]
Numerical Aperture				0.200 ± 0.015	
Chromatic Dispersion				FDDI Spec	
Backscatter Characteristics [3] Step [4]	1300 nm			≤ 0.1 ≤ 0.1	[dB] [dB]
Irregularities over fibre length Reflections				Not allowed	
Group Index of Refraction (Typical)	850 nm 1300 nm			1.482 1.477	

Fiber specifications

Modal Bandwidth - measure of signal amplitude to drop 3dB

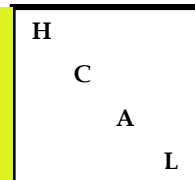
1000 MHz-km = 700-800 Mbps

HCAL fiber - 0.1 km

850nm --> 1000 MHz-km --> 7-8 Gbps

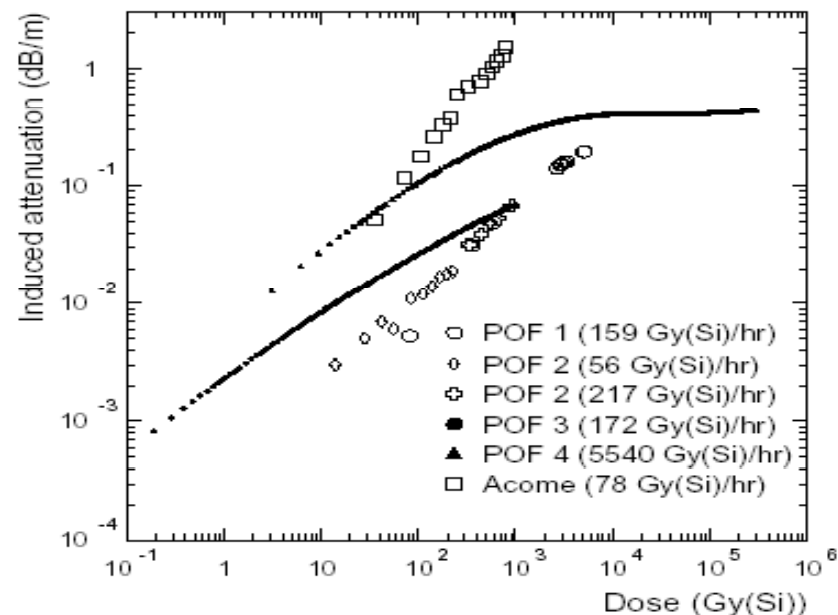


Cable



Cable requirements

- Able to transmit 1.6 Gbps over 90 m with low dispersion
 - 50/125 μm rather than 62.5/125 μm
- Very little darkening of fiber at HCAL radiation levels (3E11 n/cm² and 1kRad TID)
 - Plasma Optical Fiber – Graded-Index Multi-mode (Atlas)
 - CMS HCAL rad test of RM fiber – no measurable change in transmission
- Controlled environment \rightarrow No thermal or moisture issues (or rodents!)

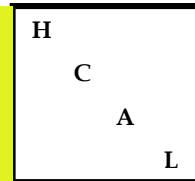


- Fiber radiation study (Atlas)
 - Plasma Optic Fiber 50/125 μm Graded Index Multi-mode Ge-doped fiber selected
 - Rad Tolerant (~ 0.1 dB/m at 800 Gy(Si) and 2E13 n/cm²)

Atlas Liquid Argon Cal (ATL-ELEC-99-001)



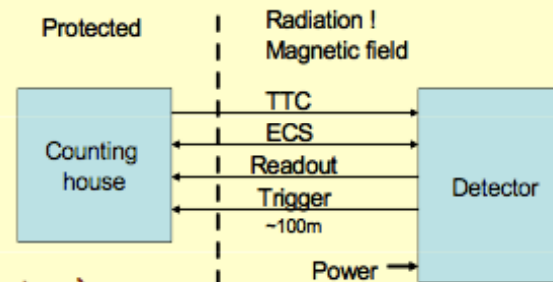
Link requirements (General)



Functions needed



- o **TTC: Trigger and timing control**
 - o Timing reference: clock(s), timing adjust, jitter, , , ?
 - o Trigger signals: trigger accept(s), trigger type, , , ?
 - o Sync control signals: reset, calibration pulse injection, , , ?
 - o Fixed and stabilized delay and latency (as short as possible)
 - o Unidirectional: down
 - o Number of signals needed ?
 - o Handling multiple FE chips: simple fan-out ?
 - o Reliability: Very high (SEU sensitive PIN/TIA in radiation !)



- o **Controls/monitoring: ECS (Experiment Control System)**
 - o Control of parameters in front-ends (with readback)
 - o Monitoring: temp, voltage, etc.
 - o Also DSS related signals ? (very high reliability required, fail safe, etc.)
 - o Effective data rate needed ? (normally not very high)
 - o Bidirectional
 - o Handling multiple FE chips: addressing, serial/parallel bus ?, other ?
 - o Reliability: high

- o **Readout**
 - o Readout of event data
 - o Maximum data rate possible
 - o Latency not an issue
 - o Unidirectional: up
 - o Handling data from multiple FE chips: Merging data streams or local event building
 - o Serial or parallel connections ?
 - o Reliability: high (single bit flips in readout data can be accepted at low rate)

- o **Trigger data**
 - o Similar to readout but constant (and short) latency may be required.

Very expensive if developed by each expt/subsystem

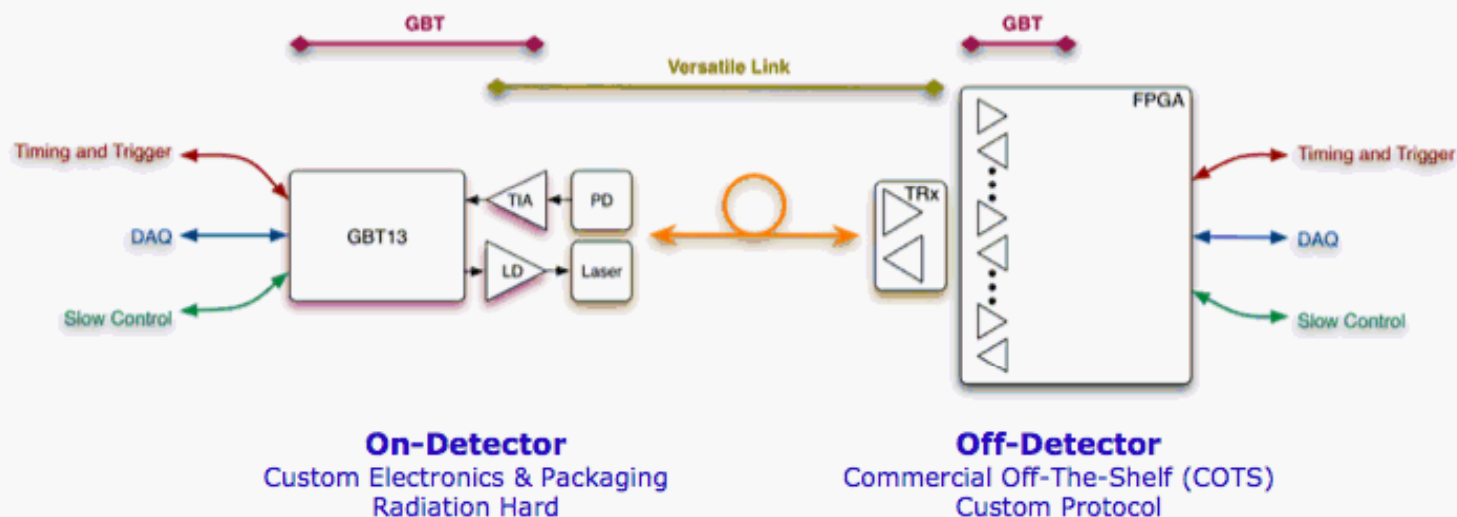


SLHC Link Project

H
C
A
L

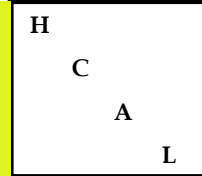
Radiation Hard Optical Link: Themes

- Two Major Themes
 - The opto-electronics, its radiation and functionality testing plus packaging
 - This work is carried out in the context of the Versatile Link
 - Versatile Link project was recently approved by CMS and ATLAS
 - The ASIC design, verification and packaging
 - This work is carried out in the context of the GBT





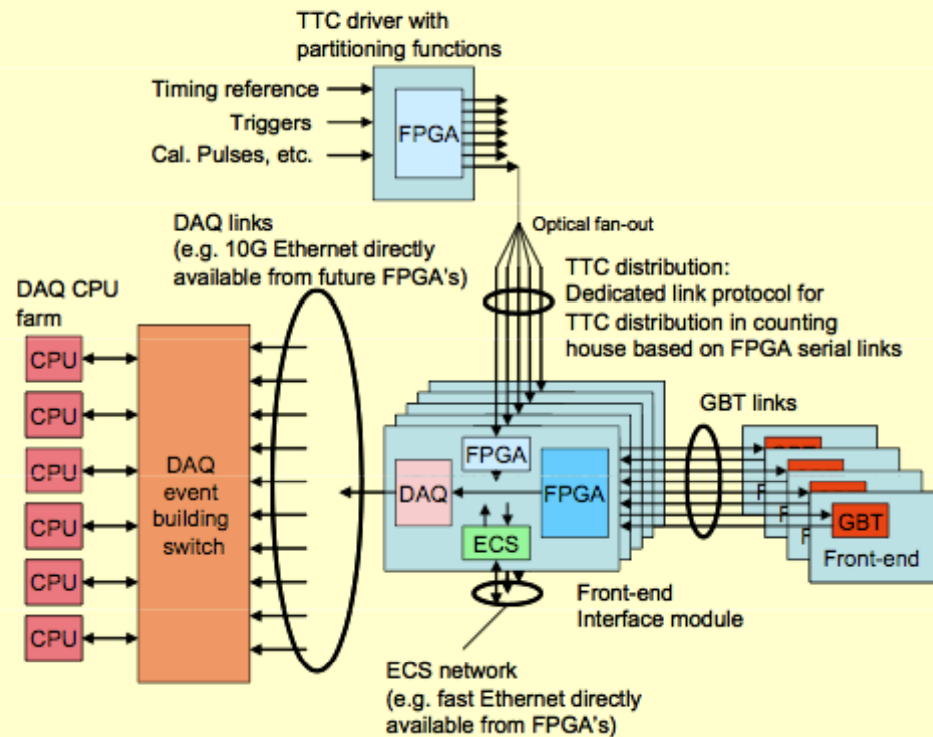
Develop Architecture



System architecture



- Decisions on the topology of the front-end link have significant effects on the global system architecture.

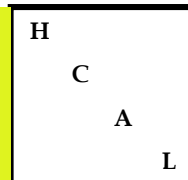


LSG Nov. 2008

slide 5

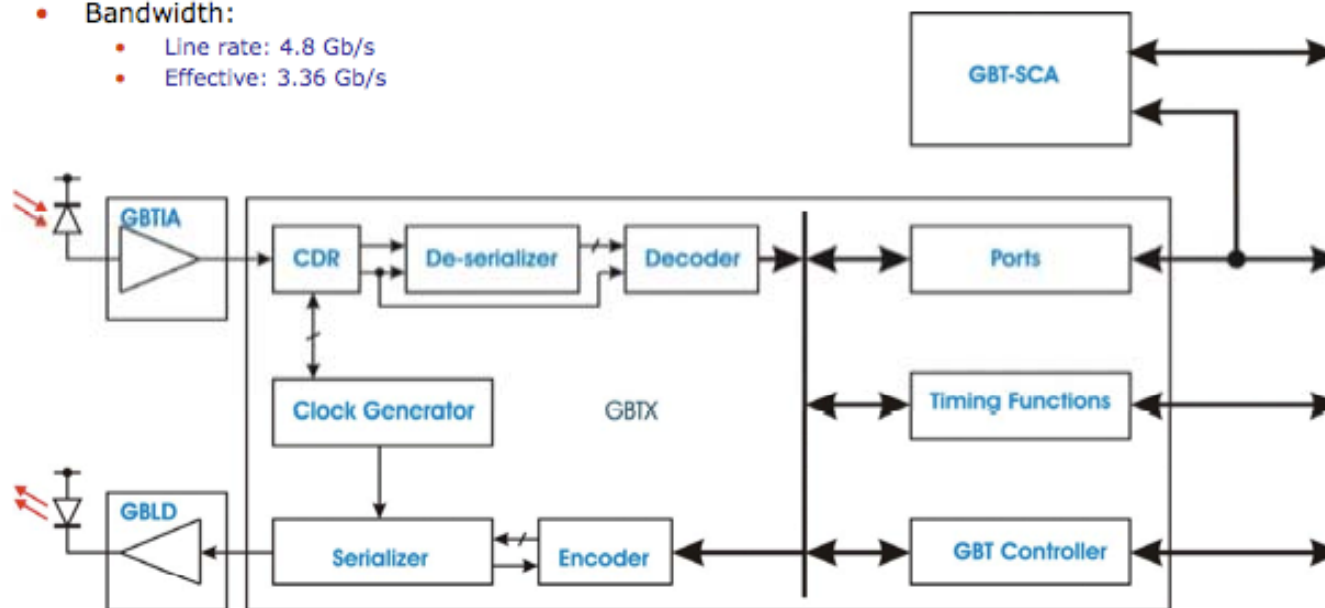


GBT chipset



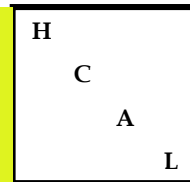
GBT Chipset

- *Radiation tolerant chipset:*
 - GBTIA: Transimpedance optical receiver
 - GBLD: Laser driver
 - GBTX: Data and timing and transceiver
 - GBT-SCA: Slow control ASIC
- *Supports:*
 - Bidirectional data transmission
 - Bandwidth:
 - Line rate: 4.8 Gb/s
 - Effective: 3.36 Gb/s
- *The target applications are:*
 - Data readout
 - TTC
 - Slow control and monitoring links.
- *Radiation tolerance:*
 - Total dose
 - Single Event Upsets



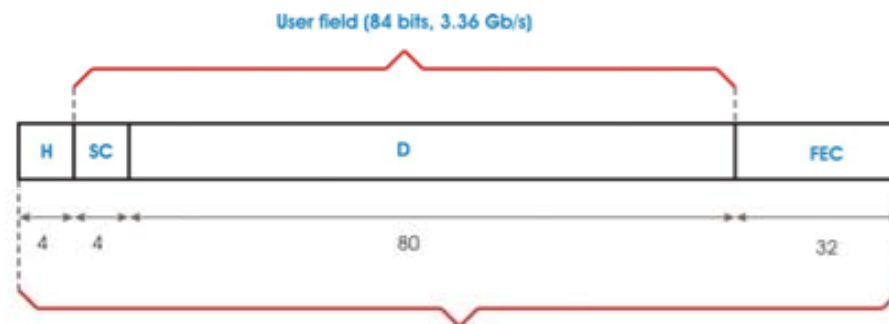


GBT Link Bandwidth



User Bandwidth: 3.36 Gbps

GBT Link Bandwidth



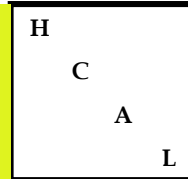
H: Header, 4 bits
 SC: GBT control, 2 bits (80 Mb/s)
 Slow control port, 2bits (80 Mb/s)
 D: DATA/TTC/EC - User data, 80 bits (3.2 Gb/s)
 FEC: Forward Error correction, 32 bits

Frame: 1 SLHC Clock Cycle (120 bits, 4.8 Gb/s)


- **Bandwidth:**
 - User: 3.36 Gb/s
 - Line: 4.8 Gb/s
- **Dedicated channels:**
 - Link control: 80 Mb/s
 - Slow control channel: 80 Mb/s
- **DC balance:**
 - Scrambler
 - No bandwidth penalty
- **Forward Error Correction and Frame Synchronization**
 - Efficiency: 73%
 - To be compared with 8B/10B: 80% (no error correction capability)
- *Link is bidirectional*
- *Link is symmetrical:*
- *Down-link highly flexible:*
 (Will be clear later when discussing e-links)
 - Can convey unique data to each frontend device that it is serving
 - "Soft" architecture managed at the control room level
 - Other schemes would require dedicated topologies that will be difficult to accommodate on a generic ASIC like the GBTX
- *Now demonstrated to be compatible with FPGAs*



VTRx Development

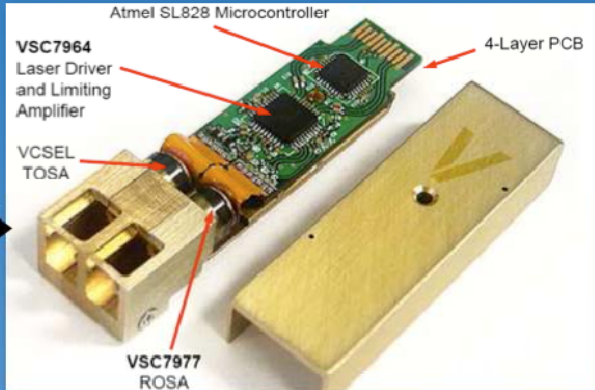
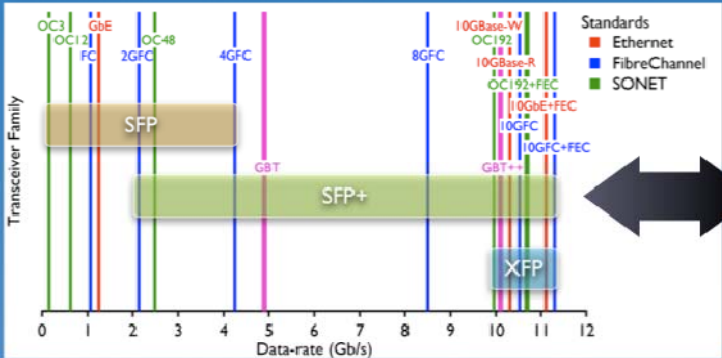


VTRx_Troska.pdf (10 pages)



VTRx Customisation

- Bi-directional Module with connector interface
 - Based upon an acknowledged standard
 - Work with Industrial partner early-on
- Low Mass & Volume
 - Minimize material, avoid metals
- Non-magnetic, capable of operating in a magnetic field
 - Requires replacement of ferrite bead used in laser bias network
- MM 850nm & SM 1310nm versions



14 November 2008 2 jan.troska@cern.ch

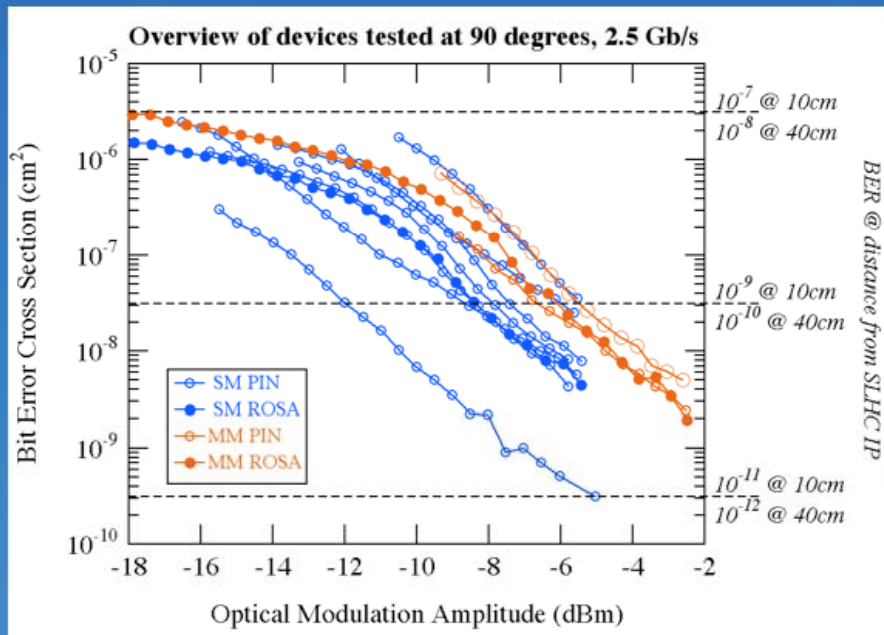


COTS SEU studies

H
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SEU Result Overview



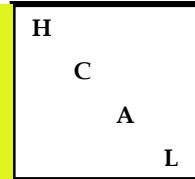
- Very Similar overall trend
 - ROSA (solid symbols) not much worse than bare PINs
 - Several orders of magnitude difference in response between devices
- BER independent of Data-rate
- Burst Errors observed
 - max. 10-bits long in PINs
 - max. 00's bits long in ROSAs
 - Error correction mandatory
- Plans:
 - Total Fluence testing of Laser, PINs and possibly TIAs and Laser Drivers in early 2009

• Device Survey:

Family	Wavelength	# Device Types (# tested)
PIN MM	850nm	2 (4)
ROSA MM	850nm	1 (2)
PIN SM	1310nm	7 (14)
ROSA SM	1310nm	1 (2)
MSM MM	850nm	1 (2)



GBT Schedule

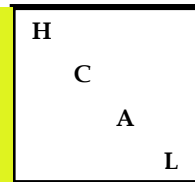


Project Schedule

- ❑ 2008
 - ❑ Design and prototyping of performance critical building blocks:
 - ❑ TIA, laser driver, PLL, serializer, de-serializer, phase shifter
 - ❑ First tests of optoelectronics components
 - ❑ (e.g. to understand SEU in PIN receivers)
 - ❑ Proceed with the link specification meetings
 - ❑ General link specification
- ❑ 2009
 - ❑ Design/prototype/test of basic serializer/de-serializer chip
 - ❑ Design/prototype/test of optoelectronics packaging
 - ❑ Detailed link specification document
- ❑ 2010
 - ❑ Prototype of "complete" link SERDES chip
 - ❑ Full prototype of optoelectronics packaging
- ❑ 2011
 - ❑ Extensive test and qualification of full link prototypes
 - ❑ System demonstrator(s) with use of full link
 - ❑ Schedule of the final production version is strongly dependent on the evolution of the LHC upgrade schedule



HCAL Needs for GBT

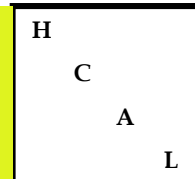


GBT - HCAL “requirements” (from Tullio)

- Investigate 8bit/10bit (64 bit/66 bit)
- Latency does matter
 - Max latency should not be greater than existing links
- Jitter needs to be better than QPLL
- Power dissipation should be lower than TTCrx/QPLL/GOL chipset
- Variations in latency of the GBT receiver (at detector) should be smaller than existing TTCrx receiver
- 8ns maximum over all range of operating conditions (temp, power supply, etc.)
- Estimate Latency Variations over a more limited range of operating conditions (15 - 35 C)



Issues - GOL

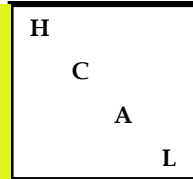


Concerns

- **Need to package GOLs (~\$25k)**
- **Test speed of GOL link**
 - Fiber speed - OK. Test final config for BER
 - Connections - will reduce max speed
- **Need to live with TTC system**
 - Will this system be maintained when other subsystems switch to GBT in Phase II?



Issues - GBT



Concerns/Comments

- Need to design HCAL system architecture/topology
- How do we establish bunch synchronizing across asynchronous links? (from Jeremy)
 - Similar to GCT problem
- GBT protocol - data frames are self synchronizing
 - No need to send idle frames (abort gaps can be used for other things (Tullio comment))
- System requirements set by large users
 - HCAL does not have many channels
 - HCAL needs will not get priority
 - Adding additional features adds “unnecessary” complexity to the chips/system
- GBT schedule is very tight for Phase I upgrades
- Tullio is starting to work on this project
 - FPGA market survey and GBT emulator for FPGA testing